Abstract:

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ABSTRACT

A package for being electrically connected to an external printed wiring board and an external electronic device ~~comprises~~ includes a substrate, a semiconductor chip, a mold compound, and a connector. The substrate is electrically connected to the external printed wiring board. The semiconductor chip is disposed on and electrically connected to the substrate. The molding compound is used for encapsulating the semiconductor chip. The connector is disposed on the substrate for electrically connecting the semiconductor chip to the external electronic device.